

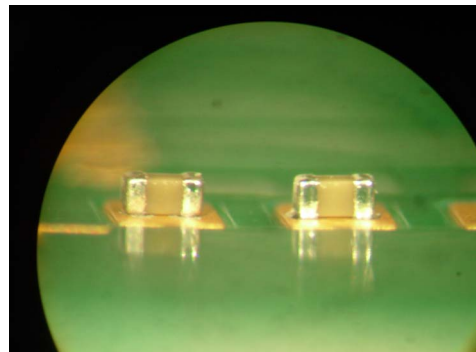
LAPLACE-Cap-SB²



Combined Machine for High Accuracy Solder Ball Jetting, Capacitor Bonding and Laser Reflow

Specifications:

- Solder ball placement, capacitor attach and laser soldering in automatic operation
- Fluxfree solder ball reflow with laser
- High throughput
- Vision system
- Bonding accuracy $\leq \pm 40 \mu\text{m}$
- Temperature control unit
- Laser class I
(IEC825, E DIN VDE 0750, 871, 837, CDRH)



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